

C25F

PROCESSES FOR THE ELECTROLYTIC REMOVAL OF MATERIALS FROM OBJECTS; APPARATUS THEREFOR

Definition statement

This place covers:

Electrolytic cleaning, degreasing, pickling or descaling

Electrolytic etching or polishing

Polishing or etching using a plasma which is generated at the surface of the workpiece by a voltage applied thereto in an electrolyte

Electrolytic stripping of metallic layers or coatings

Constructional parts, or assemblies thereof, of cells for electrolytic removal of material from objects, servicing or operating

References

Limiting references

This place does not cover:

Working of metal by the action of electric current on a workpiece, electrochemical machining, electrolytic grinding, electro-erosion	B23H
Non-mechanical removal of metallic material from surfaces	C23F
Inhibiting corrosion of metals by anodic or cathodic protection	C23F 13/00
Constructional parts or assemblies thereof, of cells for both electrolytic coating and removal	C25D 17/00
Wafer treatment	H10P
Processes specially adapted for treatment of semi-conductors or solid state devices, e.g. electrolytic etching	H10P 50/00 , H10P 50/20 , H10P 52/00 , H10P 95/70

Informative references

Attention is drawn to the following places, which may be of interest for search:

Chemical cleaning involving a liquid and additional treatment, e.g. electricity	B08B 3/10
Polishing or grinding with abrasive particles	B24B
Lapping machines using both abrasives substances and the application of electrical current	B24B 37/00
After-treatment of articles using an electrical field, without altering their shape or form	B29C 71/0081
Polishing compositions	C09G
Multistep processes for surface treatment of metallic material	C23F 17/00
Measuring using electrical means	G01B 7/00
Analyzing materials with electro-chemical means	G01N 27/00
Non-contact plasma polishing	H01J 37/00

C25F 1/00**Electrolytic cleaning, degreasing, pickling or descaling****Glossary of terms**

In this place, the following terms or expressions are used with the meaning indicated:

Electrolytic cleaning	removing impurities from a surface by electrolytic action
Electrolytic degreasing	removing grease from a surface by electrolytic action
Electrolytic pickling or de-scaling	removing oxide or scale from a surface by electrolytic action
Melt	molten salt or ionic liquid or fused bath

C25F 3/00**Electrolytic etching or polishing****Relationships with other classification places**

Methods of polishing or grinding using electric current where the electrolyte comprises abrasive material would be classified in [B24B 37/046](#)

Special rules of classification

An electrolyte specified in a document is classified in [C25F 3/00](#) even when it concerns one of the fields listed under "references" of subclass [C25F](#). Exception: electrolytes comprising abrasive material are not classified in [C25F 3/00](#).

Glossary of terms

In this place, the following terms or expressions are used with the meaning indicated:

Electrolytic etching	dissolving by - electrolytic action or - a plasma which is generated at the surface of the workpiece by a voltage applied to the electrodes in the electrolyte, such that a rough surface is obtained
Electrolytic polishing	dissolving by - electrolytic action or - by a plasma which is generated at the surface of the workpiece by a voltage applied to the electrodes in the electrolyte, such that a smooth surface is obtained

C25F 3/12**of semiconducting materials****Glossary of terms**

In this place, the following terms or expressions are used with the meaning indicated:

Semiconducting material	the material as such, not a workpiece which is a semiconductor (e.g. a wafer)
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C25F 3/14**locally****Definition statement**

This place covers:

Locally electrolytic etching where the portions to be etched are determined only by a mask or a template

C25F 3/30**of semiconducting materials****Glossary of terms**

In this place, the following terms or expressions are used with the meaning indicated:

Semiconducting material	the material as such, not a workpiece which is a semiconductor (e.g. a wafer)
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C25F 5/00**Electrolytic stripping of metallic layers or coatings****Definition statement**

This place covers:

Removing an entire layer or coating, even when this layer or coating is already partially damaged (e.g. removing NiCrAlY from a turbine blade to be reworked)